

MMSZ4689

General Description

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the Leadless package.

Features

- Compact surface mount with same footprint as mini-melf
- 500mW rating on FR-4 or FR-5 board.
- Class 3 ESD rating (>16kV) per Human Body Model

Ordering

- 7 inch reel (178mm); 8mm Tape; 3,000 units per reel.

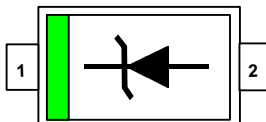
Absolute Maximum Ratings (note 1) $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
T_{STG}	Storage Temperature	-55 ~ 150	$^\circ\text{C}$
T_J	Maximum Junction Temperature	-55 ~ 150	$^\circ\text{C}$
P_D	Total Power Dissipation at 25°C Derate above 25°C	500 6.7	mW mW/ $^\circ\text{C}$
R_{QJA}	Thermal Resistance Junction to Ambient	340	$^\circ\text{C/W}$
R_{QJL}	Thermal Resistance Junction to Lead	150	$^\circ\text{C/W}$
ΔV_Z	Maximum Voltage Change (note 2)	970	mV
Lead Solder Temperature (Max 10 second duration)		260	$^\circ\text{C}$
Nominal Zener Voltage (V_Z) at 50 μA		5.1	V

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Note 2: Voltage change is equal to the difference between V_Z at 100 μA and V_Z at 10 μA .

Top Mark: CU
1: Cathode
2: Anode



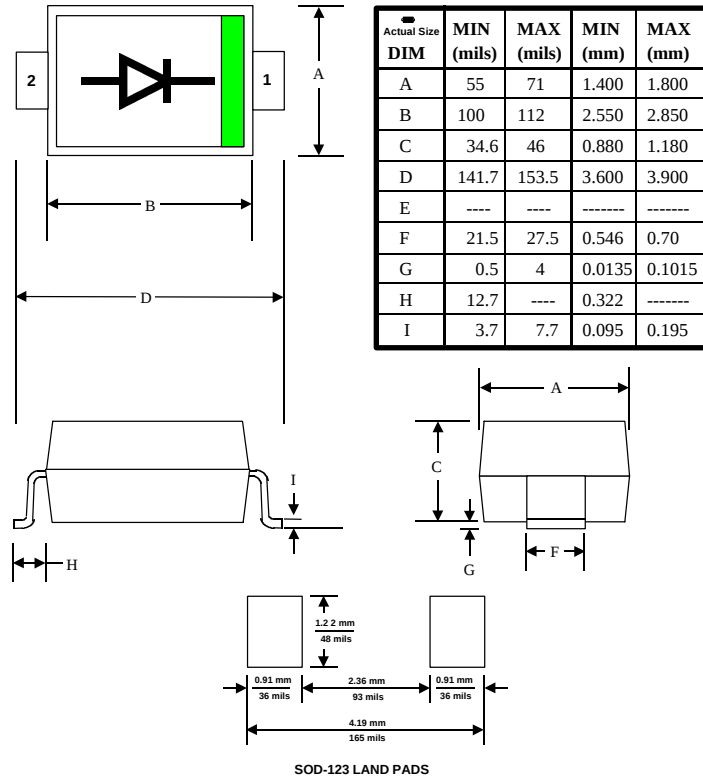
Electrical Characteristics $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Characteristics	Test Conditions	Min.	Max.	Units
V_Z	Zener Voltage	$I_{ZT} = 50\mu\text{A}$ D.C	4.85	5.36	V
I_R	Reverse Leakage	$V_R = 3.0\text{V}$		10	μA
V_F	Forward Voltage	$I_F = 10\text{mA}$		900	mV
ΔV_Z	Delta Zener Voltage (Note 2)	$I_{ZT} = 100\mu\text{A}$ to 10 μA		970	mV

SOD-123 PACKAGE

PACKAGE CODE = (D6)
Fairchild Semiconductor's Criteria

Corrected March 11, 1998



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Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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Definition of Terms

Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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